

Bill of Materials

TI DESIGNS

TIDM-VOICEBANDAUDIO

Item	Qty	Reference	Value	Part Description	Manufacturer	Manufacturer Part Number	Alternate Part	PCB Footprint	Note
1		C1, C9, C13	0.47uF	CAP, CERM, 0.47uF, 6.3V, +/-	MuRata	GRM188R60J474KA01D		0603	
2		C2, C6, C7	4.7uF	CAP, CERM, 4.7uF, 6.3V, +/-10%, X5R, 0603	MuRata	GRM188R60J475KE19D		0603	
3		C3	1uF	CAP, CERM, 1uF, 6.3V, +/-10%, X5R, 0603	MuRata	GRM185R60J105KE26D		0603	
4		C4	0.33uF	CAP, CERM, 0.33uF, 6.3V, +/-10%, X5R, 0603	MuRata	GRM188R60J334KA01D		0603	
5		C5	1800pF	CAP, CERM, 1800pF, 25V, +/-10%, X7R, 0603	MuRata	GRM188R71E182KA01D		0603	
6		C8, C14	0.1uF	CAP, CERM, 0.1uF, 6.3V, +/-10%, X7R, 0603	MuRata	GRM188R70J104KA01D		0603	
7		C10	0.015uF	CAP, CERM, 0.015uF, 16V, +/-10%, X7R, 0603	MuRata	GRM188R71C153KA01D		0603	
8		C11	0.15uF	CAP, CERM, 0.15uF, 10V, +/-10%, X5R, 0603	MuRata	GRM188R61A154KA01D		0603	
9		C12	51pF	CAP, CERM, 51pF, 50V, +/-5%, C0G/NP0, 0603	MuRata	GRM1885C1H510JA01D		0603	
10		D1	Red	LED, Red, SMD	Lite-On	LTST-C170KRKT		LED_0805	
11		J1/J3, J4/J2		Connector, Receptacle, 100mil, 10x2, Gold plated, TH	Major League Electroni	CRD-081413-A-F	SSW-110-23-F-D, Samtec	HEADER, RECEPTACLE, 100mil, 10x2	
12		J10		Header, TH, 100mil, 2x1, Gold plated, 230 mil above insulator	Samtec	TSW-102-07-G-S		2x1 Header	
13		J15		Connector, Audio Jack, 3.5mm, Stereo, SMD	CUI Inc.	SJ-3523-SMT		Audio Jack SMD	
14		MK1		Microphone, Condenser, Analog, Omnidirectional, -42DB, TH	PUI Audio	POM-2242P-C33-R		6mm DIA	
15		P1		Potentiometer	Bourns	PTV09A-4015F-A103		TH	
16		R1, R9, R12	47k	RES, 47k ohm, 5%, 0.1W, 0603	Vishay-Dale	CRCW060347K0JNEA		0603	
17		R2	130	RES, 130 ohm, 0.1%, 0.1W, 0603	Susumu Co Ltd	RG1608P-131-B-T5		0603	
18		R3	4.02k	RES, 4.02k ohm, 0.1%, 100mW, 0603	Vishay	TNPW06034K02BEEA		0603	
19		R4	3.32k	RES, 3.32k ohm, 0.1%, 100mW, 0603	Vishay	TNPW06033K32BEEA		0603	
20		R5	3.65k	RES, 3.65k ohm, 0.1%, 100mW, 0603	Vishay	TNPW06033K65BEEA		0603	
21		R6	470	RES, 470 ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-07470RL		0603	

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22		R7	1.00k	RES, 1.00k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-071KL		0603	
23		R8	3.0k	RES, 3.0k ohm, 5%, 0.1W, 0603	Yageo America	RC0603JR-073KL		0603	
24		R10	8.20k	RES, 8.20k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-078K2L		0603	
25		R11, R15	820	RES, 820 ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-07820RL		0603	
26		R13	200k	RES, 200k ohm, 1%, 0.1W, 0603	Yageo America	RC0603FR-07200KL		0603	
27		R14	51k	RES, 51kohm, 0.5%, 100mW,	Panasonic	ERA-3AED513V		0603	
28		R16, R18, R22, R24	0	RES, 0 ohm, 5%, 0.125W, 0805	Vishay-Dale	CRCW08050000Z0EA		0805	
29		R17, R19, R21, R23	DNP	RES, 0 ohm, 5%, 0.125W, 0805	Vishay-Dale	DNP		0805	
30		R20		RES, 0 ohm, 5%, 0.125W, 0805	Vishay-Dale	CRCW08050000Z0EA		0805	
31		R25	0	RES, 0 ohm, 5%, 0.125W, 0805	Vishay-Dale	DNP		0805	
32		S1		Speaker	PUI Audio	AST-03208MR-R		TH	
33		SW1	SPST	SPST Toggle Switch	Mountain Switch	108-0050-EVX		TH	
34		U1		16Mbit SPI Flash	SST	SST25VF016B		8-SOIC	
35		U2		350mW Mono Audio Power	Texas Instruments	TPA301		8SOP	
36		U3		Single 1.8-V, Micro-power, Rail-to-	Texas Instruments	TLV2760IDBVR		SOT-23 (DBV)	
37		U4		0.3 Ohm Dual SPDT Analog Switch Dual-Channel 2:1 Multiplexer/Demultiplexer	Texas Instruments	TS3A24159DGSR		VSSOP (DGS) 10	

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